

NXT-H

High plating configuration and extended lifetime solution recommended for harsh environments

With high plating grade configuration, Linxens NXT-H is one of the top corrosion-resistant solutions. This feature is perfectly suitable for payment, electronic ID and connected devices solutions. NXT-H ensures high-level of data security, longer lifetime and corrosion resistance.

Key Features

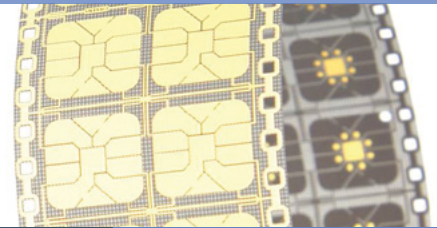
- Worldwide reference plating family
- High plating grade
- Very high corrosion resistance

Typical Product Designs

Part Number	Modules	Cavity	Chip Dimension
9X12121	8	No	3.6 x 3.65 mm
9X16001	8	✓	3.6 x 3.6 mm
9X16004	8	No	4.8 x 4.8 mm
9X23206	8	✓	3.8 x 6.6 mm
9X23207	8	No	5.6 x ≤ 8 mm
9X13901	6	✓	1.8 x 1.8 mm
9X13902	6	No	3.2 x 3 mm
9X13704	6	✓	1.8 x 1.8 mm
9X13705	6	No	3 x 3 mm
9X21002	6	✓	3.9 x 4.9 mm
9X21003	6	No	4.1 x ≤ 6 mm
9X12106	8	✓	2.44 x 2.44 mm
9X12107	8	✓	2.44 x 2.44 mm
9X12110	8	No	3.6 x 3.6 mm



MICROCONNECTORS



Overview

Material

- Film base: Standard Epoxy glass
- Adhesive: High temperature modified Epoxy MCHT
- Copper: ED29 μ

Thickness

- Total: 161 \pm 20 μ m / 167 \pm 20 μ m
- Plating Thickness
Contact side:
 - Ni: 4 (-1 +2) μ m
 - Au: 0.10 (-0.04 +0.05) μ mBack side:
 - Ni: 6 (-3 +6) μ m
 - Au: 0.30 (-0.10 +0.20) μ m

Temperature Resistance

- 3 minutes at 260°C
- 21 hours at 160°C

Plating Performance

Corrosion resistance: Very high
Chemical resistance: Very high

Compliance Labels

- ISO 10373
- ISO 7810

Application Area

- eGovernment
- Financial services
- Healthcare
- IoT

Options

- Micro-etched / Fully-etched
- Colored tape: Red, blue, orange